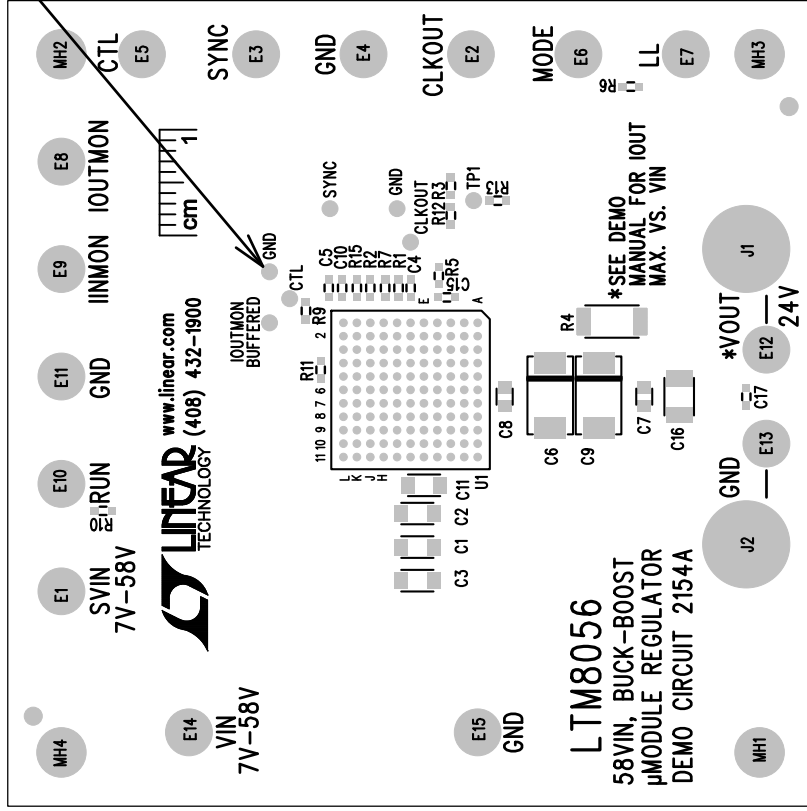


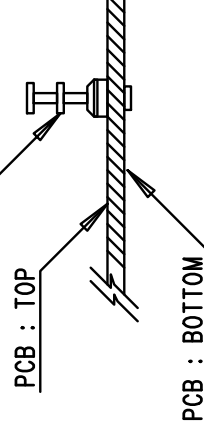
7



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
5. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
6. INSTALL 4 STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:
7. TEST POINT(7 PCS) SHOULD BE FREE OF SOLDER.

TURRETS : MILL-MAX 2501-2 OR 2308-2



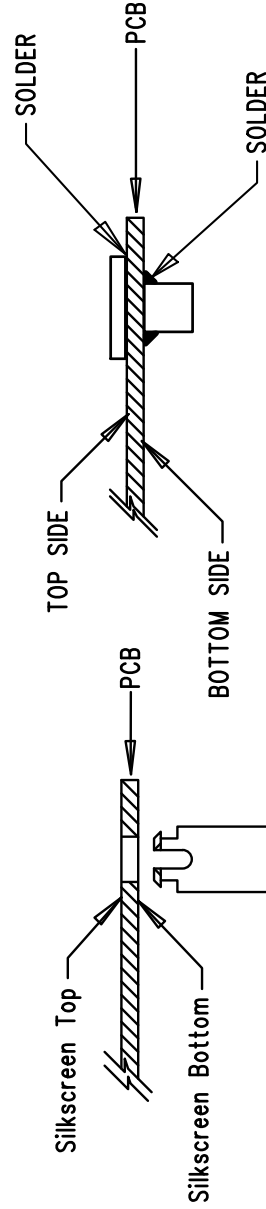
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TITLE: TOP ASSEMBLY DRAWING

58VIN, BUCK-BOOST
μMODULE REGULATOR

SIZE	IC NO.	LTM8056EY	REV.
N/A		DEMO CIRCUIT 2154A	1
FILENAME:	DC2154A-1.PCB		SHT 1 OF 2



BANANA JACK : KEYSTONE 575-4

STANDOFF, NYLON, SNAP ON.